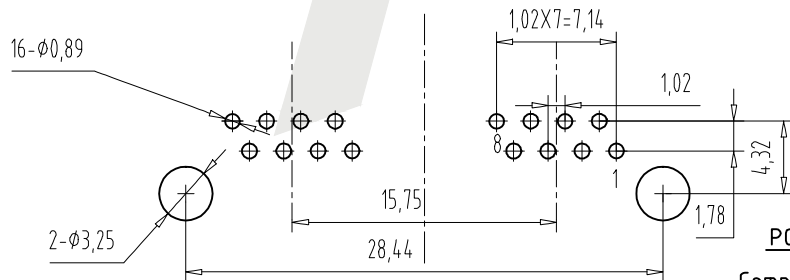
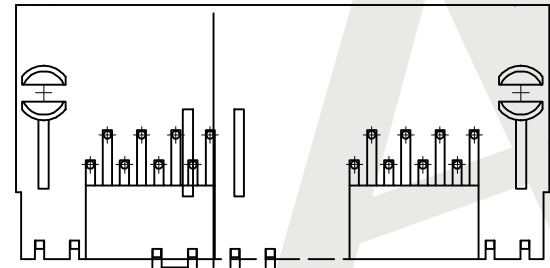
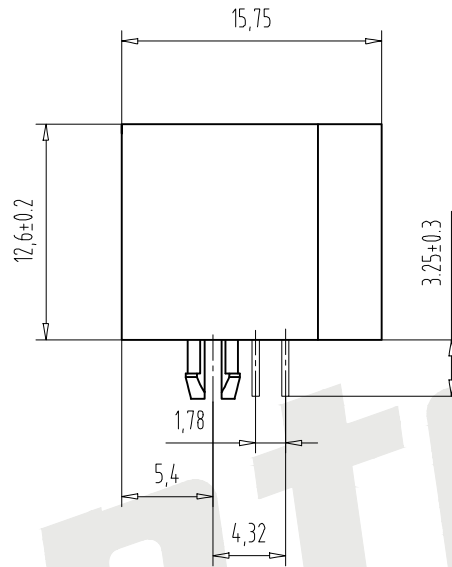
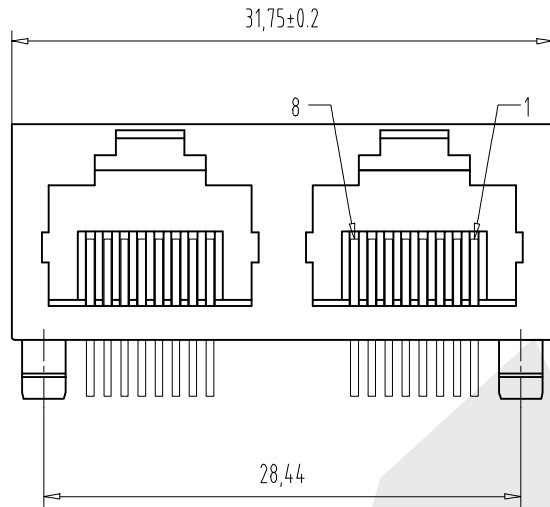


HSF



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40° C TO 85° C
2. OPERATION: 0° C TO 70° C

Order code:

ATRJ5621 - 8P - 8C - X - A - B

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)
- ④ Contact Plating  
G0: Gold flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold  
SN: Tin
- ⑤ Shield  
A: W/O Shield  
B: Half Shield  
C: Shield W/Eml  
D: Shield W/O Eml
- ⑥ Ports  
A: 1X1P G: 2X1P  
B: 1X2P H: 2X2P  
C: 1X4P I: 2X3P  
D: 1X5P J: 2X4P  
E: 1X6P K: 2X6P  
F: 1X8P L: 2X8P

Unless Otherwise specified tolerance  
X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

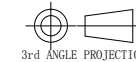
**Antenk** ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm  
DRAW Wu Feng Rong DATE 22/03/2018  
CHECK BobYang DATE 22/03/2018

TITLE: RJ11 JACK side entry,  
1X2Port Full plastic

DRAWING NO: ATRJ5621-8P8C-X-A-B

PRODUCT NO: ATRJ5621-8P8C-X-A-B



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		
6		
7		
8		